

Title (en)  
Multiconnection device

Title (de)  
Mehrfache Verbindungseinrichtung

Title (fr)  
Dispositif multi-connection

Publication  
**EP 1530262 A3 20060208 (EN)**

Application  
**EP 04256884 A 20041105**

Priority  
JP 2003379196 A 20031107

Abstract (en)  
[origin: EP1530262A2] A multi-connection type header connector, and a stack type socket connector and a horizontal type socket connector for connection thereto A multi-connection type header connector and a stack type socket and a horizontal type socket connectors for connection to the multi-connection type header is disclosed which can accomplish reduction in both the mounting area and the height. The multi-connection type header connector (100) comprises a header housing (110) that is provided with a receiving chamber (115) that concaves from the top face (111) and extends up to an end face (113) on the front side in the depth direction and a header contact (120), of which contacting part (121) is exposed to the receiving chamber (115) and of which connecting part (122) is exposed to the periphery of the bottom face of the header housing (110). A stack type socket connector (200), which has, at one end in the height direction thereof, a protruding part (211) that is to fit into the receiving chamber (115) in the height direction, and from which, at the other end, a wire (W) is led out in a direction that crosses the height direction, and the horizontal type socket contact (300). The horizontal type connector has, at the end on the rear side in the depth direction, a protruding part (311) that fits into the receiving chamber (115) in the height direction, and from which, at the end on the front side in the depth direction, a wire (W) is led out in a direction that crosses the height direction, can be selectively connected to the header connector (100).

IPC 8 full level  
**H01R 12/16** (2006.01); **H01R 13/64** (2006.01); **H01R 12/71** (2011.01); **H01R 13/46** (2006.01); **H01R 24/00** (2006.01); **H01R 27/00** (2006.01)

CPC (source: EP KR)  
**H01R 12/716** (2013.01 - EP); **H01R 13/64** (2013.01 - KR); **H01R 27/00** (2013.01 - EP)

Citation (search report)

- [A] EP 1313176 A1 20030521 - J S T MFG CO LTD [JP]
- [A] EP 0898332 A2 19990224 - SONY CORP [JP]
- [DA] PATENT ABSTRACTS OF JAPAN vol. 1996, no. 07 31 July 1996 (1996-07-31)

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**EP 1530262 A2 20050511**; **EP 1530262 A3 20060208**; CN 100505434 C 20090624; CN 1614829 A 20050511; KR 101085481 B1 20111121; KR 20050044267 A 20050512; TW 200520319 A 20050616; TW I341625 B 20110501

DOCDB simple family (application)  
**EP 04256884 A 20041105**; CN 200410088627 A 20041105; KR 20040089589 A 20041105; TW 93131997 A 20041021